

SN5470, SN7470 AND-GATED J-K POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

SDLS116 - DECEMBER 1983 - REVISED MARCH 1988

- Package Options Include Plastic and Ceramic DIPs and Ceramic Flat Packages
- Dependable Texas Instruments Quality and Reliability

description

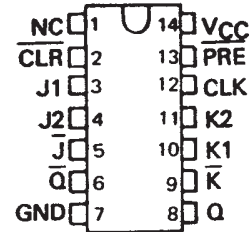
These monolithic, edge-triggered J-K flip-flops feature gated inputs, direct clear and preset inputs, and complementary Q and \bar{Q} outputs. Input information is transferred to the outputs on the positive edge of the clock pulse.

Direct-coupled clock triggering occurs at a specific voltage level of the clock pulse, and after the clock input threshold voltage has been passed, the gated inputs are locked out.

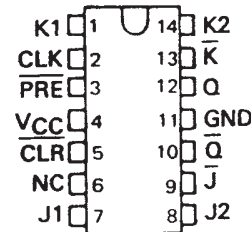
These flip-flops are ideally suited for medium-to-high-speed applications and can result in a significant saving in system power dissipation and package count where input gating is required.

The SN5470 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN7470 is characterized for operation from 0°C to 70°C .

SN5470 . . . J PACKAGE
SN7470 . . . N PACKAGE
(TOP VIEW)

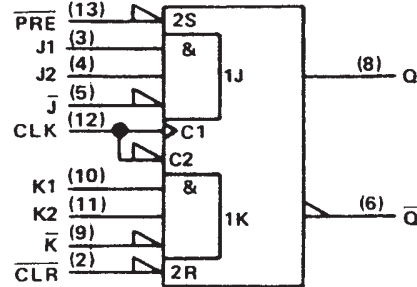


SN5470 . . . W PACKAGE
(TOP VIEW)



NC - No internal connection

logic symbol†



†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for J and N packages only.

positive logic

$$J = J1 \cdot J2 \cdot \bar{J}$$

$$K = K1 \cdot K2 \cdot \bar{K}$$

INPUTS					OUTPUTS	
PRE	CLR	CLK	J	K	Q	\bar{Q}
L	H	L	X	X	H	L
H	L	L	X	X	L	H
L	L	X	X	X	L†	L†
H	H	↑	L	L	Q ₀	Q ₀
H	H	↑	H	L	H	L
H	H	↑	L	H	L	H
H	H	↑	H	H	TOGGLE	
H	H	L	X	X	Q ₀	Q ₀

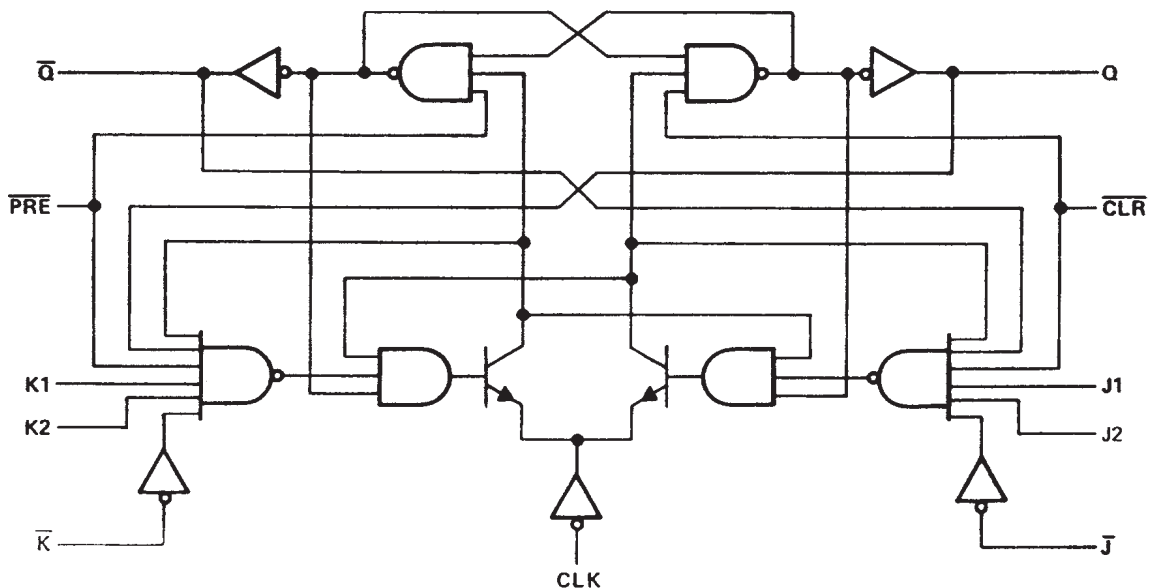
If inputs J and K are not used, they must be grounded. Preset or clear function can occur only when the clock input is low.

†This configuration is nonstable; that is, it will not persist when preset and clear inputs return to their inactive (high) level.

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FLIP-FLOPS WITH PRESET AND CLEAR

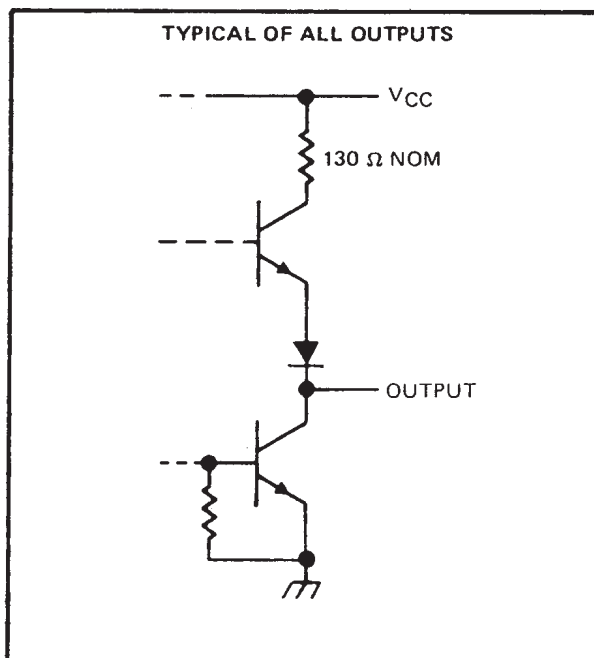
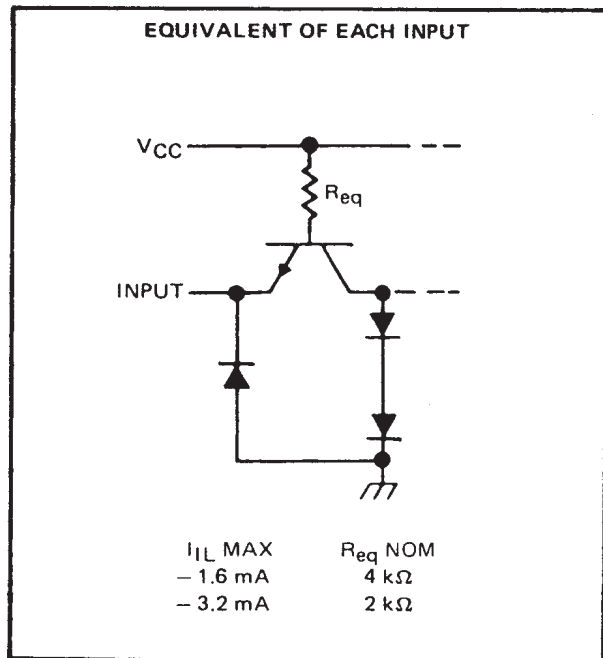
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logic diagram (positive logic)



'70-GATED J-K WITH CLEAR AND PRESET

schematics of input and outputs



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)7 V
Input voltage	5.5 V
Operating free-air temperature: SN5470	– 55°C to 125°C
SN74700°C to 70°C
Storage temperature range	– 65°C to 150°C

NOTE 1: All voltage values are with respect to network ground terminal.

recommended operating conditions

	SN5470			SN7470			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH} High-level input voltage	2			2			V
V_{IL} Low-level input voltage	0.8			0.8			V
I_{OH} High-level output current	– 0.4			– 0.4			mA
I_{OL} Low-level output current	16			16			mA
t_w Pulse duration	CLK high		20	CLK low		20	ns
	PRE or CLR low		25	PRE or CLR low		25	
	PRE or CLR low		25	PRE or CLR low		25	
t_{su} Setup time before CLK \uparrow	20			20			ns
t_h Hold time-Data after CLK \uparrow	5			5			ns
T_A Operating free-air temperature	– 55		125	0		70	°C

†‡ The arrow indicates the edge of the clock pulse used for reference: \uparrow for the rising edge, \downarrow for the falling edge.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN5470			SN7470			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	$V_{CC} = \text{MIN}, I_I = -12 \text{ mA}$	– 1.5			– 1.5			V
V_{OH}	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V}, I_{OH} = -0.4 \text{ mA}$	2.4	3.4		2.4	3.4		V
V_{OL}	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V}, I_{OL} = 16 \text{ mA}$		0.2	0.4		0.2	0.4	V
I_I	$V_{CC} = \text{MAX}, V_I = 5.5 \text{ V}$	1			1			mA
I_{IH}	PRE or CLR	80			80			μA
	All other	40			40			
I_{IL}	PRE or CLR†	– 3.2			– 3.2			mA
	All other	– 1.6			– 1.6			
$I_{OS}\S$	$V_{CC} = \text{MAX}$	– 20		– 57	– 18		– 57	mA
I_{CC}	$V_{CC} = \text{MAX},$ See Note 2	13 26			13 26			mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$.

§Not more than one output should be shorted at a time.

†Clear is tested with preset high and preset is tested with clear high.

NOTE 2: With all outputs open, I_{CC} is measured with the Q and \bar{Q} outputs high in turn. At the time of measurement, the clock input is at 4.5 V.

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switching characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$ (see note 3)

PARAMETER†	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{\max}			$R_L = 400\ \Omega$, $C_L = 15\ \text{pF}$	20	35		MHz
t_{PLH}	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$	Q or $\overline{\text{Q}}$				50	ns
t_{PHL}						50	ns
t_{PLH}	CLK	Q or $\overline{\text{Q}}$			27	50	ns
t_{PHL}					18	50	ns

† f_{\max} = maximum clock frequency; t_{PLH} = propagation delay time, low-to-high level output;
 t_{PHL} = propagation delay time, high-to-low level output.

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN5470J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125		
SN7470N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN7470N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SNJ5470J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125		
SNJ5470J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125		
SNJ5470W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI	-55 to 125		
SNJ5470W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI	-55 to 125		

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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OTHER QUALIFIED VERSIONS OF SN5470, SN7470 :

- Catalog: [SN7470](#)
- Military: [SN5470](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

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